L Number	Hits	Search Text	DB	Time stamp
1	2	solder with (high adj thermal adj conductivity near2 low adj melt\$3 adj	USPAT;	2004/10/15 16:48
		point)	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
2	4	solder and (high adj thermal adj conductivity near2 low adj melt\$3 adj	USPAT;	2004/10/15 17:03
		point)	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
3	13	high adj thermal adj conductivity near2 low adj melt\$3 adj point	USPAT;	2004/10/15 17:03
			US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
4	322	solder and (high adj thermal adj conductivity) and (low adj melt\$3 adj	USPAT;	2004/10/15 17:03
	·	point)	US-PGPUB;	
			ЕРО; ЛРО;	1
			DERWENT;	
			IBM_TDB	
5	24	solder and (high adj thermal adj conductivity) with (low adj melt\$3 adj	USPAT;	2004/10/15 17:23
		point)	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
6	356	(metal organic) adj (layer film) near2 surface near2 (cover lid)	USPAT;	2004/10/15 17:25
			US-PGPUB;	•
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
7	9	(metal organic) adj (layer film) near2 surface near2 lid	USPAT;	2004/10/15 17:25
			US-PGPUB;	
	•		ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
-	212	(metal near (layer film)) near2 surface near2 (die chip)	USPAT;	2004/10/15 14:32
			US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
-	123	((metal near (layer film)) near2 surface near2 (die chip)) and substrate	USPAT;	2004/10/15 14:33
			US-PGPUB;	
			EPO; JPO;	
•			DERWENT;	
		(((IBM_TDB	2004/10/15 15:25
-	65	(((metal near (layer film)) near2 surface near2 (die chip)) and substrate)	USPAT;	2004/10/15 15:25
		and solder	US-PGPUB;	
			EPO; JPO; DERWENT;	
		•		
		("5201064" "5509220" "5905072" "5007190" "5095412"	IBM_TDB USPAT	2004/10/15 14:59
-	9	("5291064" "5508230" "5895972" "5907189" "5985412" "6118177" "6245240" "6317326" "6300181") PN	USFAI	4004/10/13 14.39
		"6118177" "6245249" "6317326" "6390181").PN. ("4047198" "4561011" "4612601" "4748538").PN.	USPAT	2004/10/15 15:02
-	4 3	("4047198" "4561011" "4612601" "4748538").PN. ("4034468" "4034469" "4233645").PN.	USPAT	2004/10/15 15:08
	83	((metal near (layer film)) near2 surface near2 (die chip)) and solder	USPAT;	2004/10/15 16:46
-	63	(thrown heat (tayor thint)) heatz surface heatz (the only)) and solder	US-PGPUB;	#00-7/10/1J 10. 7 0
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
		L	1	<u> </u>